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**JUNG**(10) **Pub. No.: US 2022/0377931 A1**(43) **Pub. Date: Nov. 24, 2022**(54) **CONVERTER****Publication Classification**(71) Applicant: **LG INNOTEK CO., LTD.**, Seoul (KR)(72) Inventor: **Jae hoo JUNG**, Seoul (KR)(73) Assignee: **LG INNOTEK CO., LTD.**, Seoul (KR)(51) **Int. Cl.****H05K 7/20** (2006.01)**H05K 5/02** (2006.01)**H05K 5/03** (2006.01)**H05K 5/00** (2006.01)(52) **U.S. Cl.****CPC** ..... **H05K 7/2089** (2013.01); **H05K 5/0217**(2013.01); **H05K 5/03** (2013.01); **H05K****5/0026** (2013.01)(21) Appl. No.: **17/770,766**(22) PCT Filed: **Nov. 13, 2020**(86) PCT No.: **PCT/KR2020/016023**

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**ABSTRACT**

A converter comprises: a housing comprising a refrigerant flow path; a printed circuit board disposed on top of the housing and on the upper surface of which an electronic component is disposed; and a cover disposed on top of the printed circuit board and which covers the upper surface of the electronic component, wherein a heat transfer layer filled with a thermal interface material is disposed on the upper surface of the housing or the lower surface of the cover overlapping the electronic component in the vertical direction.

